

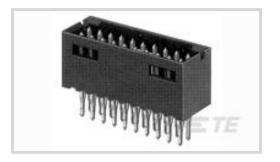
AMPMODU | AMPMODU Headers

TE Internal #: 102557-9 PCB Mount Header, Vertical, Wire-to-Board, 10 Position, 2.54 mm [. 1 in] Centerline, Fully Shrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers

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Connector System: Wire-to-Board

Number of Positions: 10

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]

PCB Mount Orientation: Vertical

Features

Product Type Features

Connector SystemWire-to-BoardHeader TypeFully ShroudedConnector & Contact Terminates ToPrinted Circuit Board

PCB Connector Assembly Type

PCB Mount Header

Configuration Features

Board-to-Board Configuration	Parallel
Connector Contact Load Condition	Fully Loaded
Number of Positions	10
Number of Rows	2
PCB Mount Orientation	Vertical
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]

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Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Nickel Tin
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	6.35 mm[.25 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Retention	With
PCB Mount Retention Type	Action/Compliant Tail
Mating Retention Type	Detent Window
Connector Mounting Type	Board Mount
Mating Alignment	With
PCB Mount Alignment	With
PCB Mount Retention	With
Housing Features	
Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	

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Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	150
Packaging Type	Tray
EU RoHS Directive 2011/65/EU	Not Compliant
Product Compliance For compliance documentation, visit the product page on TE.com>	
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EU ELV Directive 2000/53/EC	Not Compliant
China Dalle 2 Directive MUT Order No. 22, 201/	
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold

Halogen Content

Solder Process Capability

BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

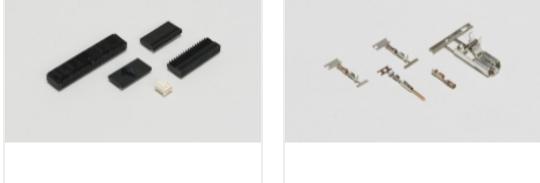
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TE Part # 87743-1 MODII KEYED BARRIER INSERT

Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

Customers Also Bought



PCB Mount Header, Vertical, Wire-to-Board, 10 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Press-Fit, AMPMODU Headers



TE Part #3-640426-9 09P MTA156 CONN ASSY 18AWG ORA

Documents

CAD Files

Customer View Model ENG_CVM_CVM_102557-9_R.2d_dxf.zip

English

3D PDF

3D

Customer View Model ENG_CVM_CVM_102557-9_R.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_102557-9_R.3d_stp.zip

English

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Product Specifications Application Specification

English